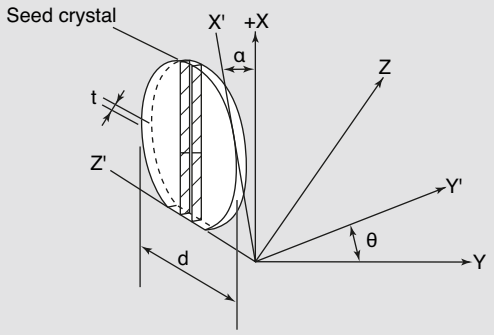
Crystal Blank

■ ST-cut Wafer

This is used for SAW devices, and the crystal used is a large-size synthetic quartz crystal with less inhomogeneousness in quality (infrared absorption coefficient α_{3585}: 0.069 or less (infrared Q value: 1.8 million or more)).



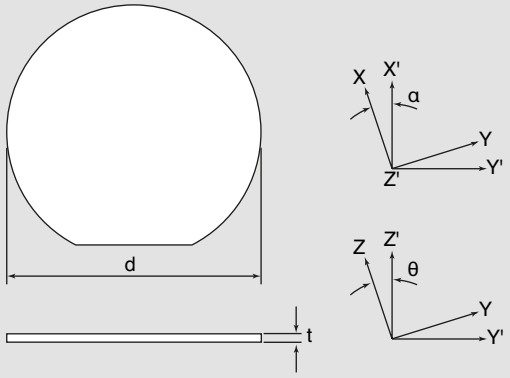
■ Standard Specifications

Specifications		Standards
Outline (d)		76.2 mm (3 inches) ±0.5 mm (round plate)
		100.0 mm±0.5 mm (round plate)
Thickness (t)		Specified thickness ±0.05 mm
Cutting angle	Direction angle (θ)	Specified angle±10'
	Inclination angle (α)	0°00'±15'
Surface finishing		Both-surface polishing

* ST-cut wafers for different specifications from the standard specifications can be manufactured upon request. Please feel free to consult with us.

■ Z-cut Wafer

We provide Z-cut wafers used for processing sensors, such as a gyro-sensor. A synthetic quartz crystal with a low etch channel density that is best suited for outline etching processing is used. Z-cut wafers with an even lower etch channel density can be delivered according to your specifications.



■ Standard Specifications

Specifications		Standards
Etch channel density		30 channels/cm^2 max.
Outline (d)		76.2 mm (3 inches) ±0.5 mm (round plate)
		100.2 mm±0.5 mm (round plate)
		Square wafers can also be manufactured.
Thickness (t)		Specified thickness ±0.05 mm
Cutting angle	Direction angle (θ)	Specified angle (0 to 2°)±10'
	Inclination angle (α)	0°00'±15'
Surface finishing		Both-surface polishing

* Z-cut wafers with specifications different to the standard specifications can be manufactured upon request. Please feel free to consult with us.